

Discription

The HESD3B12WS protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. Excellent clamping capability, low leakage, low capacitance, and fast response time provide best in class protection on designs that are exposed to ESD.

It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.

Features

- ★ Small Body Outline Dimensions
- ★ Low Body Height
- ★ Peak Power up to 350 Watts @ 8 x 20 _s Pulse
- ★ Low Leakage current
- ★ Response Time is Typically < 1 ns
- ★ IEC61000-4-2 Level 4 ESD Protection
- ★ IEC61000-4-4 Level 4 EFT Protection

Orderingin formation

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Product ID	Pack	Qty(PCS)				
HESD3B12WS	SOD-323	3000				

Absolute Ratings(Tamb = 25°C)

Symbol	Parameter	Value	Units
P _{PP}	Peak Pulse Power ($t_{p} = 8/20 \ \mu \ s$)	350	W
TL	Maximum lead temperature for soldering during 10s	260	°C
T _{stg}	Storage Temperature Range	-55 to +155	°C
T _{op}	Operating Temperature Range	-40 to +125	°C
Tj	Maximum junction temperature	150	°C
	IEC61000-4-2 (ESD) air discharge contact discharge	±30 ±30	KV
	IEC61000-4-4 (EFT)	40	А
	ESD Voltage Per Human Body Model	16	KV

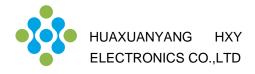


SOD-323





Circuit Diagram



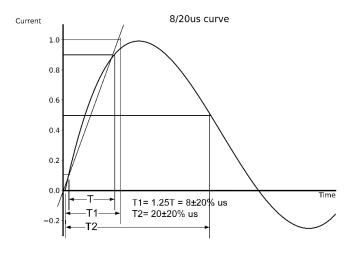
V _{RWM} (V)	I _R (uA) @ V _{RWM}	V _{BR} (V)@ I _T (Note 1)	Ι _Τ	V _C (V) @ I _{PP} =1 A*	V _c (V) @ Max I _{PP} *	І _{РР} (А)*	Р _{РК} (W)*	С (рF)
Мах	Мах	Min	mA	Тур	Max	Мах	Мах	Max
12	1.0	13.3	1	20	37	12	350	50

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.VF = 0.9V at IF = 10mA

*Surge current waveform per Figure 1.

1. V_{BR} is measured with a pluse test current I_T at an ambient temperature of $25^\circ\!\mathbb{C}$.

Typical Characteristics





Outline And Dimensions

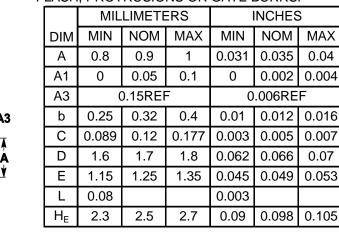
Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

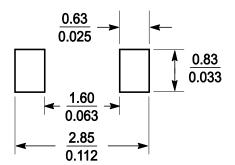
2. CONTROLLING DIMENSION: MILLIMETERS.

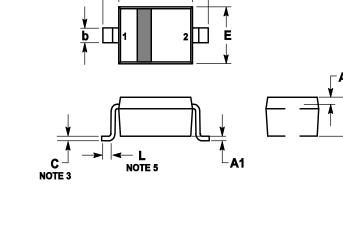
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



Soledering Footprint





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